



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Patent Application of:

Mikel R. Fulk

Serial No.: 10/059,404

Group Art Unit: 2833

Filed: January 31, 2002

Examiner: Ross N. Gushi

For: HIGH DENSITY WIRE BONDABLE CONNECTOR ASSEMBLY

Attorney Docket No.: DP-305004 (DEL 0190 PA)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Box Non-Fee Amendment, Assistant Commissioner of Patents and Trademarks, Washington, D.C. 20231 on

4/17/2003

(Date of Deposit)

*John A. Hagg*

(Signature)

AMENDMENT UNDER 37 CFR § 1.111

Box Non-Fee Amendment  
Assistant Commissioner of  
Patents and Trademarks  
Washington, D.C. 20231

Dear Sir:

This paper is in response to the first Office Action in the above-entitled application, mailed November 7, 2002, and allowing three months for response. This response is filed with a request for a two month extension of time.

The Commissioner is authorized to charge any fees which may be due or owing to Deposit Account No. 50-0476.

Please amend the above-identified application as follows:

IN THE CLAIMS

Please replace claim 1 with the following:

1. A wire bondable connector assembly comprising:  
at least one lead element including a lead portion and a carrier strip portion;  
a first coining area formed in said lead portion of said lead element;

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